

# 1200V/100A SiC HALF BRIDGE

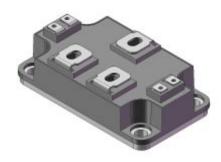
4804

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### **FEATURES**:

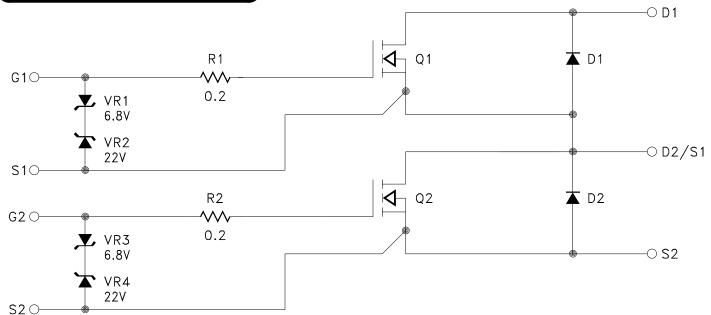
- Half Bridge Configuration
- · Silicon Carbide Mosfet Provides Ultra Fast Switching
- Silicon Carbide Diode Provides Near Zero Recovery
- 1200V Rated Voltage
- 100A Continuous Output Current
- · Internal Zener Clamps on Gates
- · Proprietary Encapsulation Provides Near Hermetic Performance
- MIL-PRF-38534 Screening Available (Modified)
- · Light Weight Domed ALSIC Baseplate
- · Robust Mechanical Design for Hi-Rel Applications
- · Ultra-Low Inductance Internal Layout
- Withstands 96 Hours HAST and Thermal Cycling (-55°C to + 125°C)



### **DESCRIPTION:**

The MSK 4804 is one of a family of plastic encapsulated modules (PEM) developed specifically for use in military, aerospace and other severe environment applications. The SiC(Silicon Carbide) technology has superior switching performance compared to Si-Based modules. The half bridge configuration and 1200V/100A rating make it ideal for use in high current motor drive and inverter applications. The Aluminum Silicon Carbide (AISiC) baseplate offers superior flatness and light weight; far better than copper or copper alloys found in most high power plastic modules. The high thermal conductivity materials used to construct the MSK 4804 allow high power outputs at elevated baseplate temperatures. Our proprietary coating, SEES™ - Severe Environment Encapsulation System - protects the internal circuitry of MSK PEM's from moisture and contamination, allowing them to pass the rugged environmental screening requirements of military and aerospace applications. MSK PEM's are also available with industry standard silicone gel coatings for a lower cost option.

# **EQUIVALENT SCHEMATIC**



### TYPICAL APPLICATIONS

- · Motor Drives
- Inverters

# ABSOLUTE MAXIMUM RATING



| VDS | Collector to Emitter Voltage      | Tst | Storage Temperature Range55° C to + 125° C |
|-----|-----------------------------------|-----|--|
| Vgs | Gate to Emitter Voltage + 25/-10V | TJ  | Junction Temperature                       |
|     | Current (Continuous)              | Tc  | Case Operating Temperature Range           |
|     | Current Pulsed (1mS) 200A         |     | MSK 4804H/E55°C to + 125°C                 |
|     | Case Isolation Voltage            |     | MSK 480440°C to +85°C                      |

# **ELECTRICAL SPECIFICATIONS**

| Parameter 6                     |   | Test Conditions                         | Group A  | MSK 4804 H/E |       |       | MSK 4804 |       |       | Units  |
|---------------------------------|---|---|----------|--------------|-------|-------|----------|-------|-------|--------|
|                                 |   |   | Subgroup | Min.         | Тур.  | Max.  | Min.     | Тур.  | Max.  | Offics |
| Drain-Source Voltage            |   | ID = 100A, VGS = 20V                    | 1        | -            | 2.4   | TBD   | -        | 2.4   | TBD   | V      |
|                                 |   |   | 2        | -            | -     | TBD   | -        | -     | TBD   | V      |
|                                 |   |   | 3        | -            | -     | TBD   | -        | -     | TBD   | V      |
| Drain-Source Leakage Current    |   | \/ma                                    | 1        | -            | -     | 1     | -        | -     | 1.2   | mΑ     |
|                                 |   | VDS = 1000V, VGS = 0V                   | 2        | -            | -     | 5     | -        | -     | -     | mA     |
|                                 |   |   | 1        | 1.0          | 1.6   | 3.5   | 0.8      | 1.6   | 3.5   | V      |
| Gate Threshold Voltage          |   | ID = 1  mA, VDS = VGS                   | 2        | 1.0          | -     | 3.5   | -        | -     | -     | V      |
|                                 |   |   | 3        | 1.0          | -     | 3.5   | -        | -     | -     | V      |
|                                 |   | ID = 100A                               | 1        | -            | 2.1   | 2.6   | -        | 2.1   | 2.8   | V      |
| Diode Forward Vol               | ltage   |   | 2        | -            | -     | TBD   | -        | -     | -     | V      |
|                                 | •   |   | 3        | -            | _     | TBD   | -        | _     | -     | V      |
| Total Gate Charge               | 1   | V = 600V, ID = 100A                     | 4        | -            | 400   | TBD   | -        | 400   | TBD   | nC     |
|                                 | V = 600V, ID =  | 100A, RG = $5\Omega$ , VGs = $-5/+20V$  | 4        | -            | 150   | TBD   | -        | 150   | TBD   | uJ     |
| <b>5</b> () <b>(</b>            | V=600V, ID=   | 50A, $RG = 5\Omega$ , $VGS = -5/ + 20V$ | 4        | -            | TBD   | -     | -        | TBD   | -     | uJ     |
| E(on) ①                         | V = 600V, ID =  | 100A, RG = $5\Omega$ , VGs = $-5/+20V$  | 5        | -            | TBD   | -     | -        | -     | -     | uJ     |
|                                 | $V = 600V$ , $ID = 50A$ , $RG = 5\Omega$ , $V = 600V$ |   | 5        | -            | TBD   | -     | -        | -     | -     | uJ     |
|                                 | V = 600V, ID =  | 100A, RG = $5\Omega$ , VGs = $-5/+20V$  | 4        | -            | 120   | TBD   | -        | 120   | TBD   | uJ     |
| E( 10) (A)                      |   | 50A, $RG = 5\Omega$ , $VGS = -5/ + 20V$ | 4        | -            | TBD   | -     | -        | TBD   | -     | uJ     |
| E(off) ①                        | V = 600V, ID =  | 100A, RG = $5\Omega$ , VGS = $-5/+20V$  | 5        | -            | TBD   | -     | -        | -     | -     | ųJ     |
|                                 | V = 600V, ID =  | 50A, $RG = 5\Omega$ , $VGS = -5/ + 20V$ | 5        | -            | TBD   | -     | -        | -     | -     | uJ     |
|                                 |   | Is = 100, di/dt = TBDA/uS               | 4        | -            | TBD   | -     | -        | TBD   | -     | n\$    |
| D'ada Da assa Das               | T' (1)  | Is = 50, di/dt = TBDA/uS                | 4        | -            | TBD   | -     | -        | TBD   | -     | nS     |
| Diode Reverse Recovery Time (1) |   | Is = 100, di/dt = TBDA/uS               | 5        | -            | TBD   | -     | -        | -     | -     | n\$    |
|                                 |   | Is = 50, di/dt = TBDA/uS                | 5        | -            | TBD   | -     | -        | -     | -     | n\$    |
|                                 | Is = 100, di/dt = TBDA/uS                             |   | 4        | -            | TBD   | TBD   | -        | TBD   | TBD   | uJ     |
| Diode Reverse Energy ①          |   | Is = 50, di/dt = TBDA/uS                | 4        | -            | TBD   | -     | -        | TBD   | -     | uJ     |
|                                 |   | Is = 100, di/dt = TBDA/u\$              | 5        | -            | TBD   | -     | -        | -     | -     | uJ     |
|                                 |   | Is = 50, di/dt = TBDA/uS                | 5        | -            | TBD   | -     | -        | -     | -     | uJ     |
| The small Design                | . 1   | IGBT @ TJ=125°C                         | -        | -            | 0.160 | 0.190 | -        | 0.160 | 0.190 | °C/W   |
| Thermal Resistance ①            |   | DIODE @ TJ = 125°C                      | -        | -            | 0.350 | 0.370 | ı        | 0.350 | 0.370 | °C/W   |

#### NOTES:

- ① Guaranteed by design but not ② Industrial grade and ("E" suffi ③ Military grade devices ("H" su ④ Subgroups 4 testing available ⑤ Subgroup 1, 4 TA = +25°C Guaranteed by design but not tested. Typical parameters are representative of actual device performance but are for reference only.
- Industrial grade and ("E" suffix) devices shall be tested to subgroup 1 unless otherwise specified. Military grade devices ("H" suffix) shall be 100% tested to subgroups 1, 2 and 3.
- Subgroups 4 testing available upon request.

2, 5  $TA = +125^{\circ}C$ 3,  $TA = -55^{\circ}C$ 

- 6 All specifications apply to both the upper and lower sections of the half bridge.
   7 Vgs= 20V unless otherwise specified.
   8 Continuous operation at or above absolute maximum ratings may adversly effect the device performance and/or life cycle.

### APPLICATION NOTES

### THERMAL CALCULATIONS

Power dissipation and maximum allowable temperature rise involve many variables working together. Drain current, PWM duty cycle and switching frequency all factor into power dissipation. DC losses or "ON-TIME" losses are simply VDS x Drain Current x PWM duty cycle. For the MSK 4804, VDS = TBD max., and at 100 amps and a PWM duty cycle of 30%, DC losses equal TBD watts. Switching losses vary proportionally with switching frequency. The MSK 4804 typical switching losses at VDS = 600V and IDS = 100A are about TBDuJ, which is simply the sum of the turn-on switching loss and the turn-off switching loss. Multiplying the switching frequency times the switching losses will result in a power dissipation number for switching. The MSK 4804, at 5KHz, will exhibit switching power dissipation of TBD watts. The total losses are the sum of DC losses plus switching losses, or in this case, TBD watts total.

TBD watts  $\times$  0.190° C/W thermal resistance equals TBD degrees of temperature rise between the case and the junction. Subtracting TBD° C from the maximum junction temperature of 150° C equals TBD° C maximum case temperature for this example.

VDS x ID x PWM duty cycle = TBD x 100 amps x 30% = TBD watts DC losses

Turn-on switching loss + Turn-off switching loss = Total switching losses = TBD + TBD = TBDuJ

Total switching loss x PWM frequency = Total switching power dissipation = TBDuJ x 5KHz = TBD watts

Total power dissipation = DC losses + switching losses = TBD + TBD = TBD watts

Junction temperature rise above case = Total power dissipation x thermal resistance

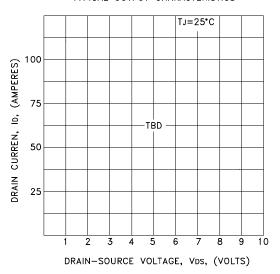
TBD watts x  $0.190^{\circ}$  C/W = TBD $^{\circ}$  C temperature rise above case

Maximum junction temperature - junction temperature rise = maximum baseplate temperature

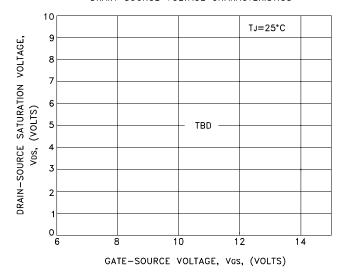
 $150^{\circ} C - TBD^{\circ} C = TBD^{\circ} C$ 

# TYPICAL PERFORMANCE CURVES

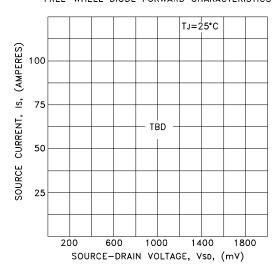
#### TYPICAL OUTPUT CHARACTERISTICS



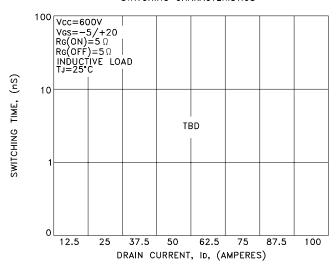
#### DRAIN-SOURCE VOLTAGE CHARACTERISTICS



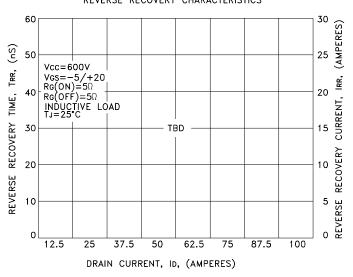
#### FREE-WHEEL DIODE FORWARD CHARACTERISTICS



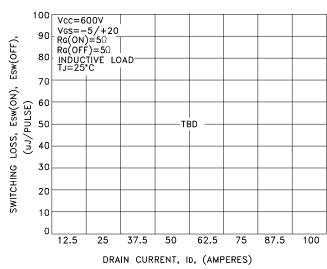
#### SWITCHING CHARACTERISTICS



### REVERSE RECOVERY CHARACTERISTICS



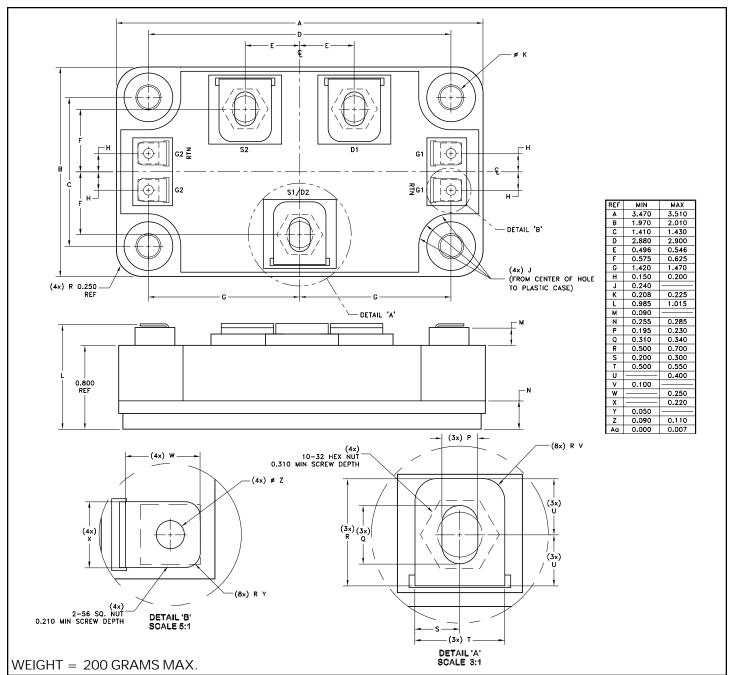
#### SWITCHING LOSS vs. DRAIN CURRENT



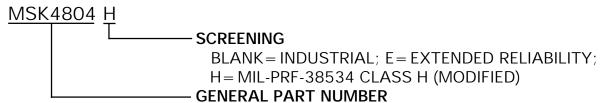
# **SCREENING CHART**

| OPERATION IN ACCORDANCE<br>WITH MIL-PRF-38534 | INDUSTRIAL       | CLASS E        | CLASS H         |
|---|------------------|----------------|-----------------|
| QUALIFICATION (MODIFIED)                      | NO               | NO             | YES             |
| ELEMENT EVALUATION                            | NO               | YES            | YES             |
| CLEAN ROOM PROCESSING                         | YES              | YES            | YES             |
| NON DESTRUCT BOND PULL SAMPLE                 | YES              | YES            | YES             |
| CERTIFIED OPERATORS                           | NO               | YES            | YES             |
| MIL LINE PROCESSING                           | YES              | YES            | YES             |
| MAX REWORK SPECIFIED                          | NO               | YES            | YES             |
| ENCAPSULANT                                   | GEL COAT         | SEES ™         | SEES TM         |
| PRE-CAP VISUAL                                | YES - INDUSTRIAL | YES - CLASS H  | YES - CLASS H   |
| TEMP CYCLE (-55°C TO +125°C)                  | NO               | YES            | YES             |
| BURN-IN                                       | NO               | YES - 96 HOURS | YES - 160 HOURS |
| ELECTRICAL TESTING                            | YES - 25°C       | YES - 25°C     | YES - FULL TEMP |
| EXTERNAL VISUAL                               | YES - SAMPLE     | YES - SAMPLE   | YES             |
| XRAY  | NO               | NO             | NO              |
| PIN FINISH                                    | NI               | NI             | NI              |

NOTE: ADDITIONAL SCREENING IS AVAILABLE SUCH AS XRAY, CSAM, MECHANICAL SHOCK, ETC. CONTACT FACTORY FOR QUAL STATUS.



# ORDERING INFORMATION



THE ABOVE EXAMPLE IS A MILITARY SCREENED MODULE.

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